



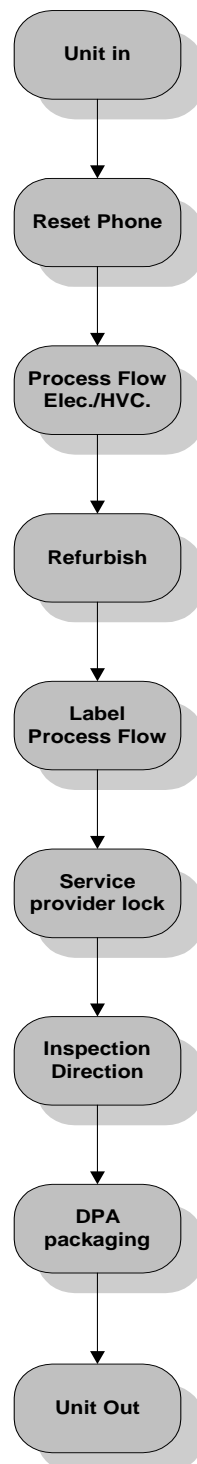
# Process Flow, Swap

Applicable for Z770i

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# 1 Process Flow



## 1.1 Explanation of the process steps

Box	Reference
Reset phone	<b>Working Instruction, Build Swap</b> – For reset of the customer's parameters in the phone, use the Master Reset function in the phone software as specified in the Working instructions. Continue with Repair Flow Std./ Adv.
Process Flow Elec. /HVC.	<b>Process Flow, Electrical or HVC.</b> - Repair the faulty unit according to the directives for the Electrical or HVC repair process. Continue with Refurbish.
Refurbish	<b>Refurbish</b> – All Swap units need to have new looking plastics as front cover, frame, keyboard etc. (this should be done when assembling the unit after repair). Continue with Process Flow, Label.
Process Flow, Label	<b>Process Flow, Label.</b> - All exchange units must be labelled according to the instructions for the Label Process Continue with Service Provider Lock test.
Service Provider Lock	<b>Service Provider Lock.</b> – Check the service provider lock. Continue with Cosmetic Inspection.
Inspection Direction	<b>Inspection Direction, Build Swap.</b> - A swap unit must be inspected according to the instructions and templates. When inspecting a complete unit, one should start with the following issues; dust in the display area, the label should be applied straight and have a good printing quality and the unit must be free from fingerprints, stains, oil, grease and other faults deterring the neat impression. Continue with DPA-packaging.
DPA-packaging	<b>Working Instruction, Build Swap.</b> - Pack the DPA according to the instruction.

## 2 Revision history

Rev.	Date	Changes / Comments
1	2008-03-13	First Release